

### Description

The **SiT5155** is a ±0.5 ppm MEMS Super-TCXO engineered for high accuracy GNSS based positioning and timing applications.

By leveraging SiTime’s unique DualMEMS™ temperature sensing and TurboCompensation™ technology, the SiT5155 delivers the most stable timing in the presence of environmental stressors – air flow, temperature perturbation, vibration, shock and electromagnetic interference (EMI). This device also integrates multiple on-chip regulators, providing power supply noise filtering and eliminating the need for a dedicated external LDO.

The SiT5155 offers three device configurations that can be ordered with the associated [ordering codes](#):

- 1) TCXO with non-pullable output frequency
- 2) VCTCXO allowing voltage control of output frequency
- 3) DCTCXO enabling digital control of the output frequency through the I<sup>2</sup>C interface

SiT5155 can be factory-programmed to any combination of frequency, stability, voltage, and pull range. This programmability enables designers to optimize the clock configuration while eliminating the long lead time and customization cost associated with quartz TCXOs where each frequency is custom built.

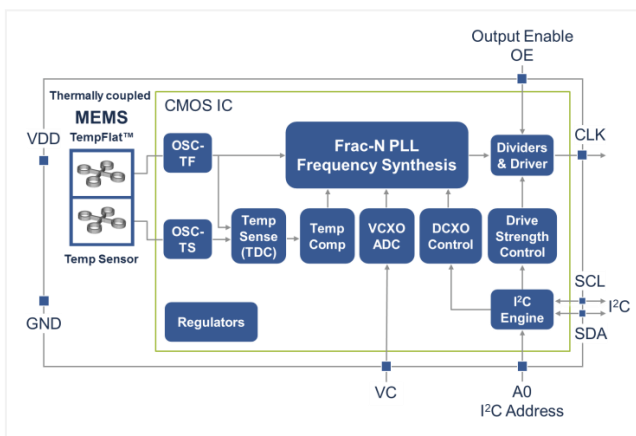
### Features

- 13 common GNSS frequencies
- Excellent dynamic stability under airflow and rapid temperature change
  - ±0.5 ppm over-temperature stability
  - ±15 ppb/°C frequency slope ( $\Delta F/\Delta T$ )
  - 3e-11 ADEV at 10 second averaging time
- No activity dips or micro jumps
- Resistant to shock, vibration and board bending
- Up to ±3200 ppm pull range (VCTCXO or DCTCXO)
- Digital frequency pulling (DCTCXO) via I<sup>2</sup>C
  - Digital control of output frequency and pull range
  - Frequency pull resolution as low as 5 ppt (0.005 ppb)
- -40°C to +85°C operating temperature, contact SiTime for +105°C option
- 2.5V, 2.8V, 3.0V and 3.3V supply voltage
- On-chip regulators, eliminating the need for the external LDO
- LVCMOS or clipped sinewave output
- RoHS and REACH compliant, Pb-free, Halogen-free and Antimony-free

### Applications

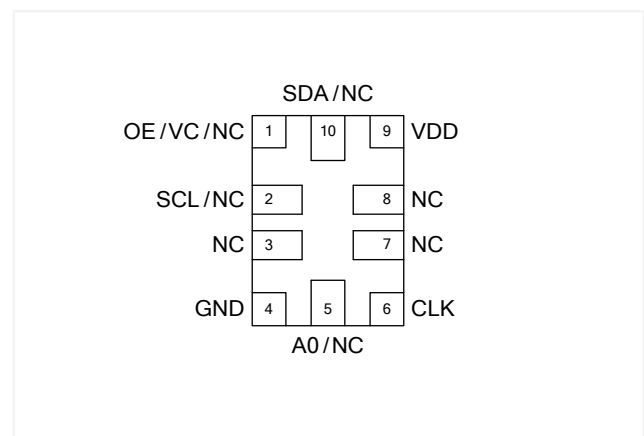
- Precision GNSS for agriculture, construction and Surveying
- Precision GNSS for Mobile mapping, marine and aerospace
- GPS, Galileo, Beidou and other GNSS systems

### Block Diagram



**Figure 1. SiT5155 Block Diagram**

### 5.0 x 3.2 mm Package Pinout



**Figure 2. Pin Assignments (Top view)**  
(Refer to Table 9 for Pin Descriptions)

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## Electrical Characteristics

All Min and Max limits are specified over temperature and rated operating voltage with 15 pF output load unless otherwise stated. Typical values are at 25°C and 3.3V Vdd

**Table 1. Output Characteristics**

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>Frequency Coverage</b>						
Output Frequency Range	F	10, 10.949297, 16.3676, 16.367667, 16.368, 16.369, 16.384, 20, 24.5535, 25, 26, 40			MHz	
<b>LVC MOS Output Characteristics</b>						
Duty Cycle	DC	45	–	55	%	
Rise/Fall Time	Tr, Tf	–	1	–	ns	10% - 90% Vdd
Output Voltage High	VOH	90%	–	–	Vdd	I <sub>OH</sub> = -6 mA, (Vdd = 3.3 V, 3.0 V, 2.8 V, 2.5 V)
Output Voltage Low	VOL	–	–	10%	Vdd	I <sub>OL</sub> = 6 mA, (Vdd = 3.3 V, 3.0 V, 2.8 V, 2.5 V)
<b>Clipped Sinewave Output Characteristics</b>						
Output Voltage Level	V <sub>out</sub>	0.8	–	1.2	V	Measured peak-to-peak swing at any Vdd
<b>Frequency Stability</b>						
Frequency Stability over Temperature	F <sub>stab</sub>	-0.5	–	+0.5	ppm	Referenced to (f <sub>max</sub> + f <sub>min</sub> )/2 over the specified temperature range
Frequency vs. Temperature Slope	ΔF/ΔT	–	±15	–	ppb/°C	F <sub>stab</sub> = ±0.5 ppm
Dynamic Frequency Change during Temperature Ramp	F <sub>dynamic</sub>	–	±0.13	–	ppb/s	F <sub>stab</sub> = ±0.5 ppm, 0.5°C/min temperature ramp rate
Initial Tolerance	F <sub>init</sub>	-1	–	+1	ppm	Initial frequency at 25°C inclusive of solder-down shift at 48 hours after 2 reflows
Supply Voltage Sensitivity	F <sub>vdd</sub>	–	±20	–	ppb	Vdd ±5%
Output Load Sensitivity	F <sub>load</sub>	–	±10	–	ppb	LVC MOS output, 15 pF ±10%
		–	±10	–	ppb	Clipped sinewave output, 10kΩ, 10 pF ±10%
First Year Aging	F <sub>1y</sub>	–	±1	–	ppm	At 25°C
<b>Start-up Characteristics</b>						
Start-up Time	T <sub>start</sub>	–	5	–	ms	Time to first pulse, measured from the time Vdd reaches 90% of its final value
First Pulse Accuracy	T <sub>stability</sub>	–	10	–	ms	Time to first accurate pulse within rated stability, measured from the time Vdd reaches 90% of its final value

Table 2. DC Characteristics

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>Supply Voltage</b>						
Supply Voltage	Vdd	2.25	2.5	2.75	V	Contact SiTime for 2.25V to 3.63V continuous supply voltage support
		2.52	2.8	3.08	V	
		2.7	3.0	3.3	V	
		2.97	3.3	3.63	V	
<b>Current Consumption</b>						
Current Consumption	IDD	–	40.5	–	mA	F = 20 MHz, No Load
OE Disable Current	I <sub>od</sub>	–	40	–	mA	OE = GND, output is weakly pulled down
<b>Temperature Range</b>						
Operating Temperature Range	T <sub>use</sub>	-20	–	+70	°C	Extended commercial
		-40	–	+85	°C	Industrial. Contact SiTime for 105 °C support

Table 3. Input Characteristics

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>Input Characteristics – OE Pin</b>						
Input Impedance	Z <sub>in</sub>	–	100	–	kΩ	Internal pull up to Vdd
Input High Voltage	V <sub>IH</sub>	70	–	–	%	
Input Low Voltage	V <sub>IL</sub>	–	–	30	%	
<b>Frequency Tuning Range – Voltage Control or I<sup>2</sup>C mode</b>						
Pull Range	PR	±6.25, ±10, ±12.5, ±25, ±50, ±80, ±100, ±125, ±150, ±200, ±400, ±600, ±800, ±1200, ±1600, ±3200			ppm	
<b>Voltage Control Characteristics</b>						
Upper Control Voltage	VC <sub>U</sub>	90%	–	–	Vdd	
Lower Control Voltage	VC <sub>L</sub>	–	–	10%	Vdd	
Control Voltage Input Impedance	VC <sub>z</sub>	10	–	–	MΩ	
Control Voltage Input Bandwidth	VC <sub>c</sub>	–	10	–	kHz	Contact SiTime for other input bandwidth options
Frequency Change Polarity		Positive				
Pull Range Linearity		–	0.5	–	%	
<b>I<sup>2</sup>C Interface Characteristics, 1 MHz, 200 Ohm, 550 pF (Max I<sup>2</sup>C Bus Load)</b>						
Input Voltage Low	V <sub>IL</sub>	–	–	0.3	V	
Input Voltage High	V <sub>IH</sub>	0.7	–	–	V	
Output Voltage Low	V <sub>OL</sub>	–	–	0.4	V	
Output Current High	I <sub>OL</sub>	21	–	–	mA	
Leakage in high impedance mode	I <sub>leak</sub>	5.5	–	24	μA	0.1 Vdd < VOUT < 0.9 Vdd
Input Hysteresis	V <sub>hys</sub>	0.2	–	0.4	V	Vdd = 3.3V
		0.2	–	0.3	V	Vdd = 2.5V
Input Capacitance	C <sub>in</sub>	–	–	3	pF	
Rise Time	Tr	–	–	120	ns	
Fall Time	Tf	30	–	60	ns	Vdd = 3.3V, 30% to 70%
		40	–	75	ns	Vdd = 2.5V, 30% to 70%

**Table 4. Jitter & Phase Noise**

Parameters	Symbol	Min.	Typ.	Max.	Unit	Condition
<b>Jitter</b>						
RMS Phase Jitter (random)	T_phj	–	0.35	–	ps	f = 10 MHz, Integration bandwidth = 12 kHz to 5 MHz
Spurs		–	-104	–	dBc	f = 10 MHz, 12 kHz to 5 MHz offsets
RMS Period Jitter	T_jitt	–	2	–	ps	f = 10 MHz per JESD65 standard
Peak Cycle-to-Cycle Jitter	T_jitt_cc	–	10	–	ps	f = 10 MHz per JESD65 standard
<b>Phase Noise</b>						
1 Hz offset		–	-70	–	dBc/Hz	f = 10 MHz, TCXO and DCTCXO modes, and VCTCXO mode with ±6.25 ppm pull range
10 Hz offset		–	-100	–	dBc/Hz	
100 Hz offset		–	-130	–	dBc/Hz	
1 kHz offset		–	-145	–	dBc/Hz	
10 kHz offset		–	-152	–	dBc/Hz	
100 kHz offset		–	-155	–	dBc/Hz	
1 MHz offset		–	-162	–	dBc/Hz	
5 MHz offset		–	-165	–	dBc/Hz	

**Table 5. Absolute Maximum Limits**

Attempted operation outside the absolute maximum ratings may cause permanent damage to the part. Actual performance of the IC is only guaranteed within the operational specifications, not at absolute maximum ratings.

Parameter	Test Conditions	Value	Unit
Storage Temperature		-65 to 125	°C
Continuous Power Supply Voltage Range (Vdd)		-0.5 to 4	V
Human Body Model (HBM) ESD Protection	JESD22-A114	–	V
Soldering Temperature (follow standard Pb-free soldering guidelines)		260	°C
Junction Temperature <sup>[1]</sup>		130	°C

Note:

1. Exceeding this temperature for an extended period of time may damage the device.

**Table 6. Thermal Considerations<sup>[2]</sup>**

Package	θJA, 4 Layer Board (°C/W)	θJA, 2 Layer Board (°C/W)	θJC, Bottom (°C/W)
Ceramic 5.0 x 3.2 mm	TBD	TBD	TBD

Note:

2. Refer to JESD51 for θJA and θJC definitions, and reference layout used to determine the θJA and θJC values in the above table.

**Table 7. Environmental Compliance**

Parameter	Test Conditions	Value	Unit
Mechanical Shock Resistance	MIL-STD-883F, Method 2002	20,000	g
Mechanical Vibration Resistance	MIL-STD-883F, Method 2007	70	g
Temperature Cycle	JESD22, Method A104	–	–
Solderability	MIL-STD-883F, Method 2003	–	–
Moisture Sensitivity Level	MSL1 @260°C	–	–

## Device Configurations and Pin-outs

Table 8. Device Configurations

Configuration	Pin 1	Pin 5	I <sup>2</sup> C Function	I <sup>2</sup> C Programmable Parameters
TCXO	OE/NC	NC	No	N/A
VCTCXO	VC	NC	No	N/A
DCTCXO	OE/NC	A0/NC	Yes	Frequency Pull Range, Frequency Pull Value, Output Enable control

### Pin-out Top Views

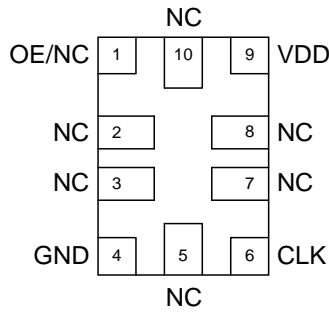


Figure 3. TCXO

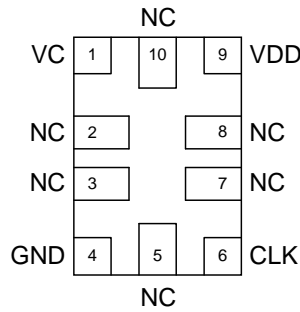


Figure 4. VCTCXO

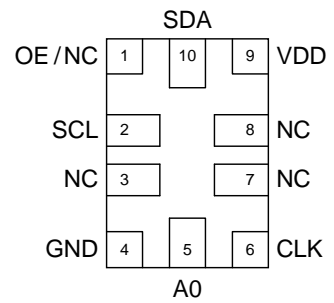


Figure 5. DCTCXO

Table 9. Pin Description

Pin	Symbol	I/O	Internal Pull-up/Pull Down Resistor	Function
1	OE/NC/VC	OE – Input	100 kΩ Pull-Up	H <sup>[3]</sup> : specified frequency output L: output is high impedance. Only output driver is disabled
		NC – No Connect	-	H or L or Open: No effect on output frequency or other device functions
		VC – Input	-	Control Voltage in VCTCXO Mode
2	SCL/NC	SCL - Input	200 kΩ Pull-Up	I <sup>2</sup> C Serial Clock Input for DCTCXO Option. NC for TCXO and VCTCXO Options.
		NC – No Connect	-	H or L or Open: No effect on output frequency or other device functions
3	NC	No Connect	-	H or L or Open: No effect on output frequency or other device functions
4	GND	Power	-	Connect to ground
5	A0/NC	A0 – Input	100 kΩ Pull-Up	Device I <sup>2</sup> C address when the address selection mode is via the A0 pin. This pin is NC when the I <sup>2</sup> C device address is specified in the ordering code. A0 Logic Level I <sup>2</sup> C Address 0 1100010 1 1101010
		NC – No Connect	-	H or L or Open: No effect on output frequency or other device functions
6	CLK	Output	-	LVC MOS or clipped sinewave oscillator output
7	NC	No Connect	-	H or L or Open: No effect on output frequency or other device functions
8	NC	No Connect	-	H or L or Open: No effect on output frequency or other device functions
9	VDD	Power	-	Connect to VDD <sup>[4]</sup>
10	SDA/NC	SDA – Input/Output	200 kΩ Pull-Up	I <sup>2</sup> C Serial Data for DCTCXO Option. NC for TCXO and VCTCXO Options.
		NC - No Connect	-	H or L or Open: No effect on output frequency or other device functions

**Notes:**

- In OE mode, a pull-up resistor of 10 kΩ or less is recommended if pin 1 is not externally driven. If pin 1 needs to be left floating, use the NC option.
- 0.1 μF capacitor in parallel with a 10 μF capacitor are required between Vdd and GND.

## Test Circuit Diagrams for LVCMOS and Clipped Sinewave Outputs

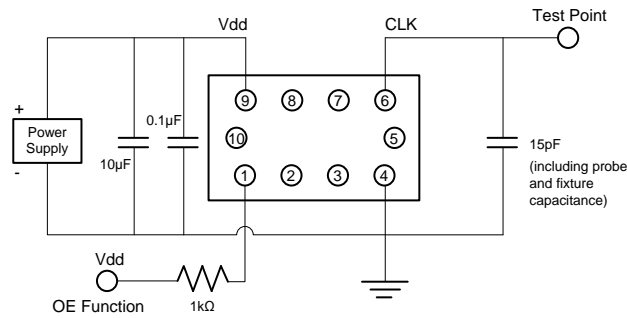


Figure 6. LVCMOS Test Circuit (OE Function)

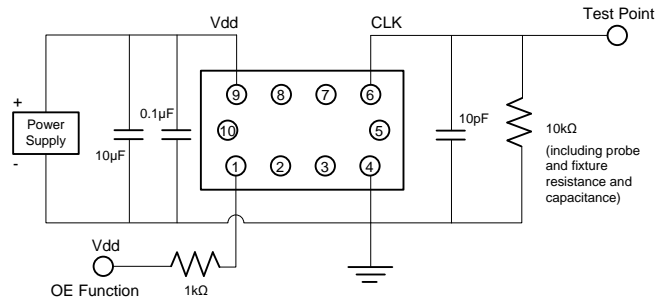


Figure 7. Clipped Sinewave Test Circuit (OE Function)

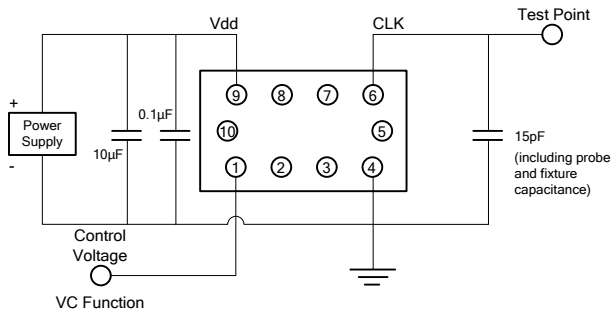


Figure 8. LVCMOS Test Circuit (VC Function)

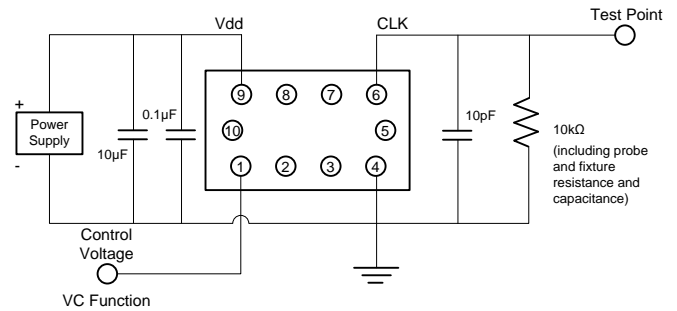


Figure 9. Clipped Sinewave Test Circuit (VC Function)

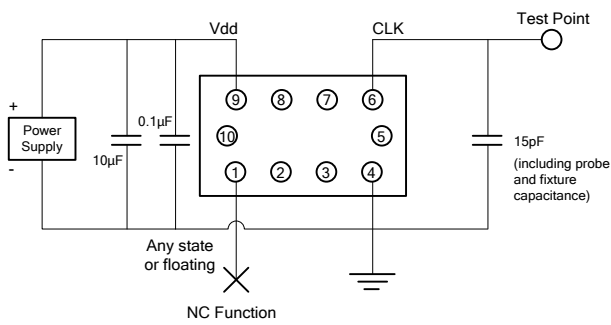


Figure 10. LVCMOS Test Circuit (NC Function)

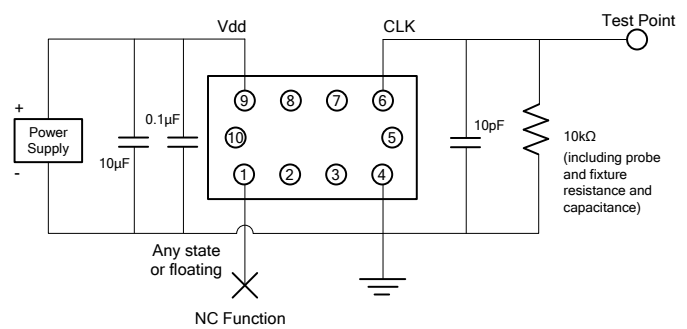


Figure 11. Clipped Sinewave Test Circuit (NC Function)

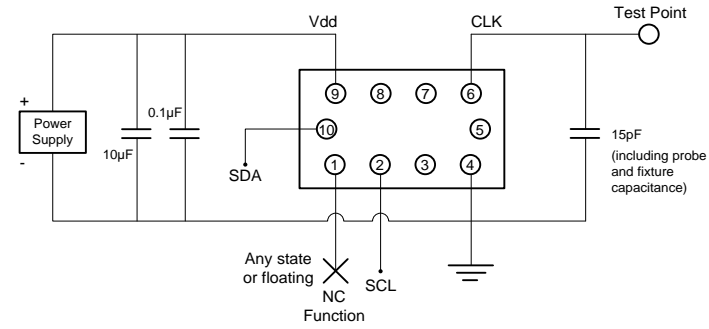


Figure 12. LVC MOS Test Circuit (I<sup>2</sup>C Control)

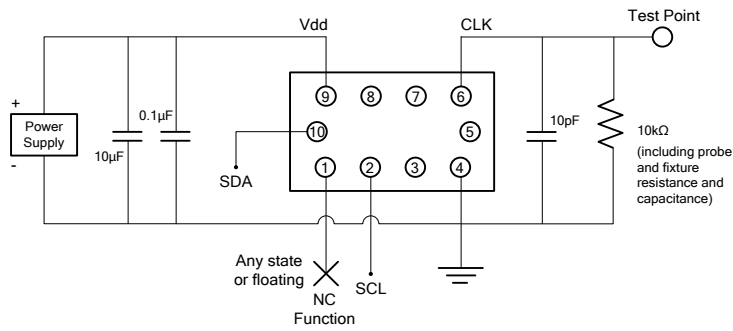
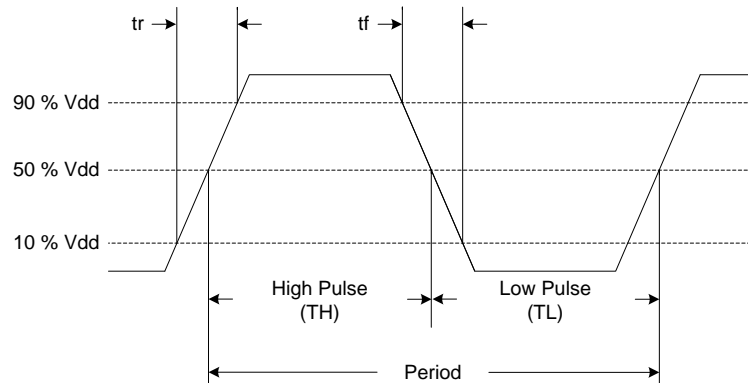
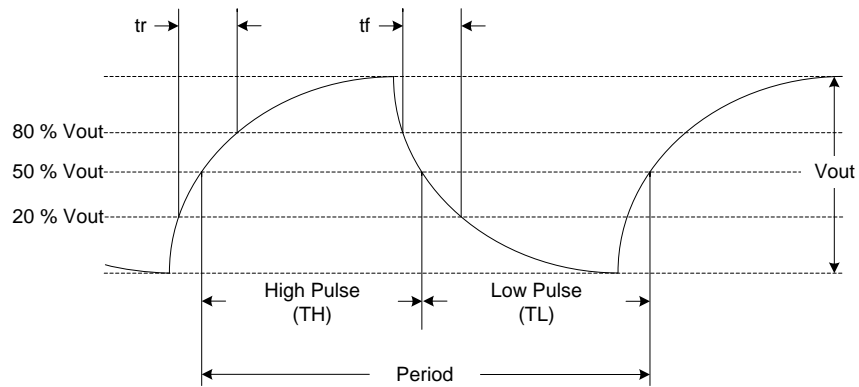


Figure 13. Clipped Sinewave Test Circuit (I<sup>2</sup>C Control)

**Waveforms<sup>[5]</sup>**



**Figure 14. LVCMOS Waveform Diagram**

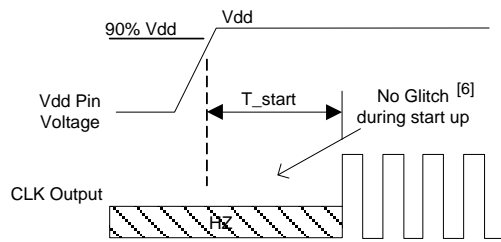


**Figure 15. Clipped Sinewave Waveform Diagram**

**Notes**

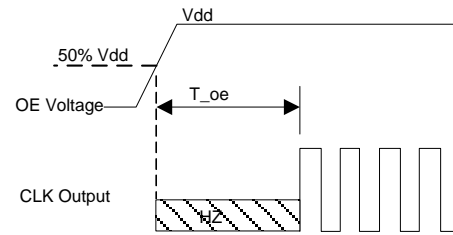
5. Duty Cycle is computed as  $Duty\ Cycle = TH/Period$ .

## Timing Diagrams



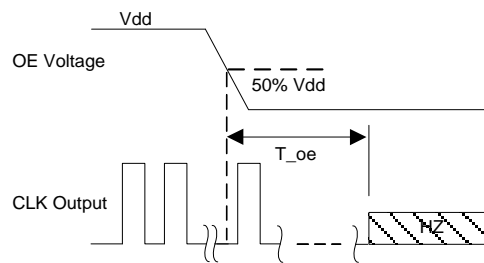
T\_start: Time to start from power-off

**Figure 16. Startup Timing (OE Mode)**



T\_oe: Time to re-enable the clock output

**Figure 17. OE Enable Timing (OE Mode Only)**



T\_oe: Time to put the output in High Z mode

**Figure 18. OE Disable Timing (OE Mode Only)**

**Note:**

6. SiT5155 has “no runt” pulses and “no glitch” output during startup or coming out of the output disable mode.

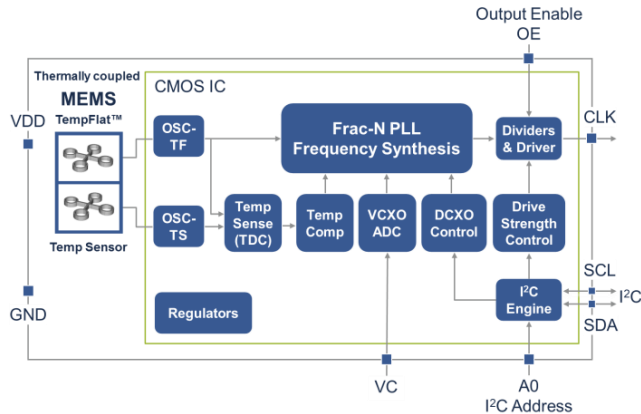
## Architecture Overview

Based on SiTime's innovative Elite Platform™, the SiT5155 delivers exceptional dynamic performance, i.e. resilience to environmental stressors such as shock, vibration and fast temperature transients. Underpinning the Elite platform are SiTime's unique DualMEMS™ temperature sensing architecture and TurboCompensation™ technology.

DualMEMS is a noiseless temperature sensing scheme. It consists of two MEMS resonators fabricated on the same die substrate. The TempFlat™ resonator is designed with a flat frequency characteristic over temperature whereas the temperature sensing resonator is by design sensitive to temperature changes. The ratio of frequencies between these two resonators provides an accurate reading of the resonator temperature with 30  $\mu$ K resolution.

By placing the two MEMS resonators on the same die, this temperature sensing scheme eliminates the thermal lag and gradients between the resonator and the temperature sensor, an inherent weakness of legacy quartz TCXOs.

The DualMEMS temperature sensor is then combined with a state-of-the-art temperature compensation circuit in the CMOS IC. The TurboCompensation design, with >100 Hz compensation bandwidth, achieves dynamic frequency stability that is far superior to any quartz TCXO. The 7<sup>th</sup> order compensation polynomial enables additional optimization of frequency stability and frequency slope over temperature within any specific temperature range of choice for a given system design.



**Figure 19. Elite Architecture**

The Elite platform also incorporates a high resolution, low noise frequency synthesizer along with the industry standard I<sup>2</sup>C bus. This unique combination enables system designers to digitally control the output frequency in steps as low as 5 ppt (parts per trillion) and over a wide range up to  $\pm$ 3200 ppm.

Please visit [www.sitime.com/technology/mems-oscillators/architecture/elite-dualmems](http://www.sitime.com/technology/mems-oscillators/architecture/elite-dualmems) for more information regarding the Elite platform and its benefits.

## Functional Overview

The SiT5155 is designed for maximum flexibility with an array of factory programmable options, enabling system designers to configure this precision device for optimal performance in a given application.

### Frequency Stability

The SiT5155 is engineered to deliver the smallest frequency-over-temperature slope ( $\Delta F/\Delta T$ ) of any  $\pm$ 0.5 ppm TCXO on the market. The lower  $\Delta F/\Delta T$  enables the GNS receivers to maintain robust satellite lock under air flow and rapid temperature changes.

**Table 10. Stability Grades vs. Ordering Codes**

Frequency Stability Over Temperature	Frequency Slope ( $\Delta F/\Delta T$ )	Ordering Code
$\pm$ 0.5 ppm	$\pm$ 15 ppb/ $^{\circ}$ C	K

### Output frequency and format

The SiT5155 can be programmable to one of the commonly use GNSS oscillator frequencies.

The device supports both LVCMOS and clipped sinewave output. Ordering codes for the output format are shown below:

**Table 11. Output Formats vs. Ordering Codes**

Output Format	Ordering Code
LVCMOS	"_"
Clipped Sinewave	"C"

### Output Frequency Tuning

In addition to the non-pullable TCXO, the SiT5155 can also support output frequency tuning through either an analog control voltage (VCTCXO) or I<sup>2</sup>C (DCTCXO).

Sixteen pull range options from  $\pm$ 6.25 ppm to  $\pm$ 3200 ppm are supported in both VCTCXO and DCTCXO configurations. The DCTCXO is recommended to ensure the best phase noise for pull range of  $\pm$ 12.5 ppm or above. It also eliminates any sensitivity to the voltage control line noise in a typical VCTCXO implementation, therefore simplifying board level design and layout.

In the DCTCXO configuration, a user can either specify a desired I<sup>2</sup>C bus address via the appropriate order code, or choose a pre-configured address with pull up/pull down resistors on the A0 pin (pin 5). The pull range can also be reprogrammed via I<sup>2</sup>C to any supported pull range option.

**Pin 1 Configuration (OE, VC, or NC)**

Pin 1 of the SiT5155 can be factory-programmed to support three modes: Output Enable (OE), Voltage Control (VC) or No Connect (NC).

**Table 12. Pin Configuration Options**

Pin 1 Configuration	Operating Mode	Output
OE	TCXO	Active or High-Z
NC	TCXO/DCTCXO	Active
VC	VCTCXO	Active

When pin 1 configured as OE pin, the device output is guaranteed to operate in one of the following two states:

- At the frequency specified in the part number when Pin 1 is pulled to logic high
- In Hi-Z mode with weak pull down when pin 1 is pulled to logic low.
- No Connect (NC) mode

When pin 1 is NC, the device is guaranteed to output the frequency specified in the part number at all times, regardless of the logic level on pin 1.

In the VCTCXO configuration, the user can fine-tune the output frequency from the nominal frequency specified in the part number by varying pin 1 voltage. The guaranteed allowable variation of the output frequency is specified as pull range. A VCTCXO part number must contain a valid pull range ordering code.

## Device Configurations and Design Considerations

The SiT5155 supports 3 device configurations – TCXO, VCTCXO and DCTCXO. The TCXO and VCTCXO options are directly compatible with the quartz TCXO and VCTCXO. The DCTCXO configuration provides performance enhancement by eliminating VCTCXO’s sensitivity to control voltage noise with an I<sup>2</sup>C digital interface for frequency tuning.

## TCXO Configuration

In the TCXO configuration, the device generates a fixed frequency output. The frequency is specified by the user in the frequency field of the device ordering code and factory-programmed. Other factory programmable options include supply voltage, output types (LVCMOS or clipped sinewave) and pin 1 functionality (OE or NC)

Refer to the [ordering information](#) section at the end of the datasheet for a list of all ordering options.

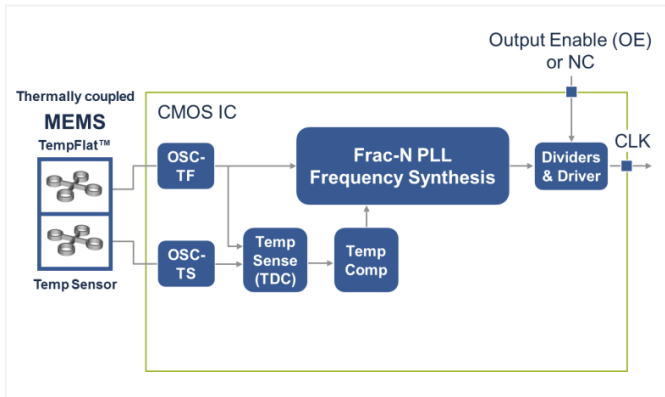


Figure 20. Block Diagram - TCXO

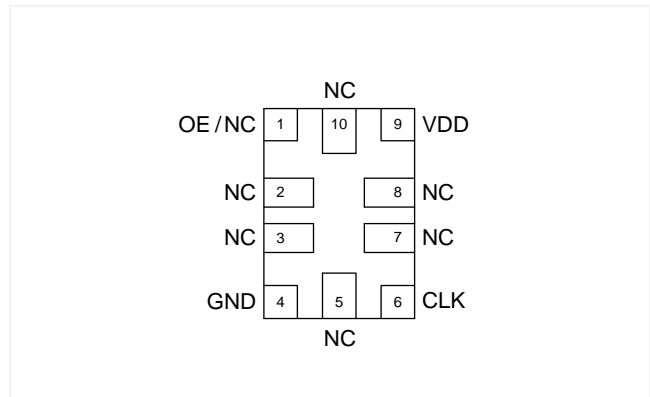


Figure 21. Top View – TCXO

### VCTCXO Configuration

VCTCXO is a frequency control device whose output frequency is an approximately linear function of control voltage applied to the voltage control pin, VCTCXOs have a number of use cases including the VCO portion of a jitter attenuation/jitter cleaner PLL Loop.

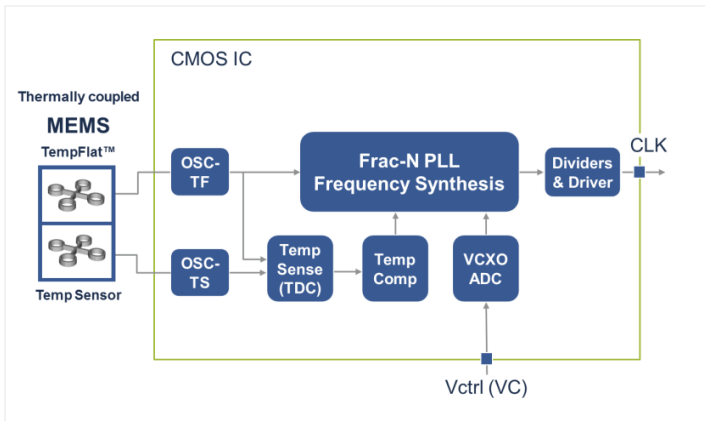
The SiT5155 VCTCXO has several inherent advantages over quartz VCTCXOs:

- 1) <0.5% frequency pull linearity vs 5% to 10% typical of quartz VCTCXOs.
- 2) Widest pull range with 16 options: ±6.25ppm, ±10 ppm, ±12.5 ppm, ±25 ppm, ±50 ppm, ±80 ppm, ±100 ppm, ±125 ppm, ±150 ppm, ±200 ppm, ±400 ppm, ±600 ppm, ±800 ppm, ±1200 ppm, ±1600 ppm, ±3200 ppm vs. ±5 ppm pull range from quartz VCTCXOs.

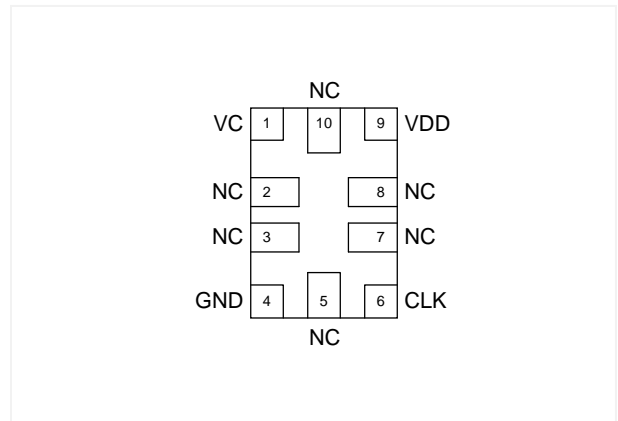
The SiT5155 achieves 10x better linearity and more pull range options via the fractional feedback divider of the PLL rather than pulling the resonator. Quartz based VCTCXOs by contrast changes output frequency by varying the capacitive load of the crystal resonator with varactor diodes, resulting in poor linearity and limited pull ranges.

Note that the output frequency of the VCTCXO is proportional to the analog control voltage applied to pin 1. Because this control signal is analog and directly controls the output frequency, care must be taken to minimize noise on this pin.

The nominal output frequency is factory programmed per the customer's request to 6 digits of precision and is defined as the output frequency when the control voltage equals  $V_{dd}/2$ . The maximum output frequency variation from this nominal value is set by the pull range which is also factory programmed to the customer's desired value and specified by the ordering code. The [ordering information section](#) shows all the ordering options and associated ordering codes.



**Figure 22. Block Diagram - VCTCXO**



**Figure 23. Top View - VCTCXO**

**Linearity**

In any VCTCXO, there will be some deviation of the FV characteristic from an ideal straight line. Linearity is the ratio of this maximum deviation to the total pull range, expressed as a percentage. Figure 24 below shows the typical pull linearity of a SiTime VCTCXO. The linearity is very high relative to most quartz offerings because the frequency pulling is achieved with the PLL rather than varactor diodes used in quartz and is 0.5% maximum.

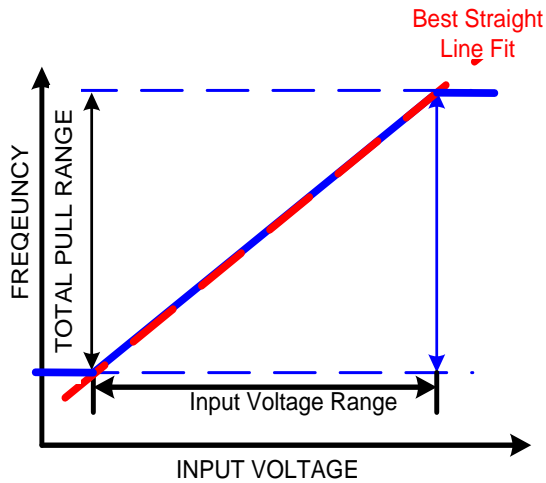


Figure 24. Typical SiTime VCTCXO Linearity

**FV Characteristic Slope  $K_V$**

The slope of the FV characteristic is a critical design parameter in many low bandwidth PLL applications. The slope is the derivative of the FV characteristic – the deviation of frequency divided by the control voltage change needed to produce that frequency deviation, over a small voltage span, as shown below:

$$K_V = \frac{\Delta f_{out}}{\Delta V_{in}}$$

It is typically expressed in kHz/volt, MHz/volt, ppm/volt, or similar units. Slope is usually called “ $K_V$ ” based on terminology used in PLL designs.

The extreme linear characteristic of the SiTime SiT5155 VCTCXO family means that there is very little  $K_V$  variation across the whole input voltage range (typically <1%), significantly reducing the design burden on the PLL designer. Figure 25 below illustrates the typical  $K_V$  variation.

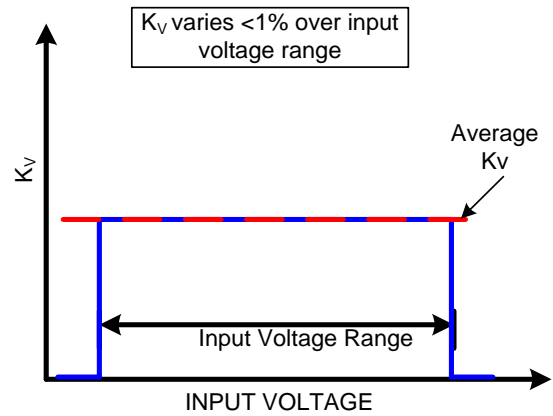


Figure 25. Typical SiTime  $K_V$  Variation

**Control Voltage Bandwidth**

Control voltage bandwidth, sometimes called “modulation rate” or “modulation bandwidth”, is the rate at which the output frequency can track an input voltage change. The ratio of the output frequency variation to the input voltage variation, previously denoted by  $K_V$ , has a low-pass characteristic in most VCTCXOs. The modulation rate is defined as the modulation rate for which the  $K_V$  is reduced by 3 dB relative to  $K_V$  for DC inputs swept in the same voltage range.

For example, a part with a ±25 ppm pull range and a 0-3V control voltage can be regarded as having an average  $K_V$  of 16.67 ppm/V (50ppm/3V = 16.67 ppm/V). Applying an input of 1.5V DC ± 0.5V (1.0 V to 2.0V) causes an output frequency change of 16.67 ppm (±8.33 ppm). If the control voltage bandwidth is specified as 8 kHz, the peak-to-peak value of the output frequency change will be reduced to 16.67 ppm/√2 or 11.8 ppm, as the frequency of the control voltage change is increased to 8 kHz.

### Pull Range, Absolute Pull Range

Pull range (PR) is the amount of frequency deviation that will result from changing the control voltage over its maximum range under nominal conditions.

Absolute pull range (APR) is the guaranteed controllable frequency range over all environmental and aging conditions. Effectively, it is the amount of pull range remaining after taking into account frequency stability tolerances over variables such as temperature, power supply voltage, and aging, i.e.:

$$APR = PR - F_{\text{stability}} - F_{\text{aging}}$$

where  $F_{\text{stability}}$  is the device frequency stability due to initial tolerance and variations on temperature, power supply, and load.

Figure 26 shows a typical SiTime VCTCXO FV characteristic. The FV characteristic varies with conditions, so that the frequency output at a given input voltage can vary by as much as the specified frequency stability of the VCTCXO. For such VCTCXOs, the frequency stability and APR are independent of each other. This allows very wide range of pull options without compromising frequency stability.

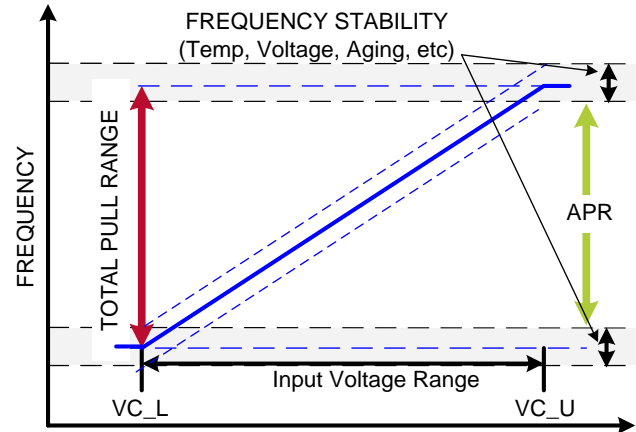


Figure 26. Typical SiTime VCTCXO FV Characteristic

The upper and lower control voltages are the specified limits of the input voltage range as shown on Figure 26 above. Applying voltages beyond the upper and lower voltages do not result in noticeable changes of output frequency. In other words, the FV characteristic of the VCTCXO saturates beyond these voltages. Figures 1 and 2 show these voltages as Lower Control Voltage (VC\_L) and Upper Control Voltage (VC\_U).

Table 13 below shows the pull range and corresponding APR values for each of the frequency vs. temperature ordering options for both the VCTCXO and the DCTCXO which will be described in the next section.

Table 13. VCTCXO, DCXO Pull Range, APR Options<sup>[7]</sup>

Pull Range Ordering Code	Device Option(s)	Pull Range ppm	APR ppm ±0.5 ppm option
T	VCTCXO, DCTCXO	±6.25	±2.75
R	VCTCXO, DCTCXO	±10	±6.5
Q	VCTCXO, DCTCXO	±12.5	±9.0
M	VCTCXO, DCTCXO	±25	±21.5
B	VCTCXO, DCTCXO	±50	±46.5
C	VCTCXO, DCTCXO	±80	±76.5
E	VCTCXO, DCTCXO	±100	±96.5
F	VCTCXO, DCTCXO	±125	±121.5
G	VCTCXO, DCTCXO	±150	±146.5
H	VCTCXO, DCTCXO	±200	±196.5
X	VCTCXO, DCTCXO	±400	±396.5
L	VCTCXO, DCTCXO	±600	±596.5
Y	VCTCXO, DCTCXO	±800	±796.5
S	VCTCXO, DCTCXO	±1200	±1196.5
Z	VCTCXO, DCTCXO	±1600	±1596.5
U	VCTCXO, DCTCXO	±3200	±3196.5

**Notes:**

7. APR includes ±1 ppm solder down shift, frequency stability vs. temperature (±0.5 ppm) and 20-year aging (±2 ppm)

### DCTCXO Configuration

The DCTCXO option offers digital control of the output frequency. The output frequency is controlled by writing frequency control words over the I<sup>2</sup>C interface.

There are several advantages of DCTCXOs relative to VCTCXOs:

- 1) Frequency Control Resolution as low as 5 ppt. This high resolution minimizes accumulated time error in synchronization applications.
- 2) Lower system cost – A VCTCXO may need a Digital to Analog Converter (DAC) to drive the control voltage input. In a DCTCXO, the frequency control is achieved digitally by register writes to the control registers via I<sup>2</sup>C, thereby eliminating the need for a DAC.
- 3) Better Noise Immunity – The analog signal used to drive the voltage control pin of a VCTCXO can be sensitive to noise and the trace over which the signal is routed can be susceptible to noise coupling from the system. The DCTCXO does not suffer from analog noise coupling since the frequency control is performed digitally through I<sup>2</sup>C.
- 4) No Frequency Pull non-linearity. The frequency pulling is achieved via fractional feedback divider of the PLL, eliminating any pull non-linearity concern which is typical of quartz based VCTCXOs. This improves dynamic performance in closed loop operations.
- 5) Programmable Wide Pull Range – The DCTCXO pulling mechanism is via the fractional feedback divider and is therefore not constrained by resonator pullability as in quartz based solutions. The SiT5155 offers 16 frequency pull range options from ±6.25ppm to ±3200ppm, thereby giving system designers great flexibility.

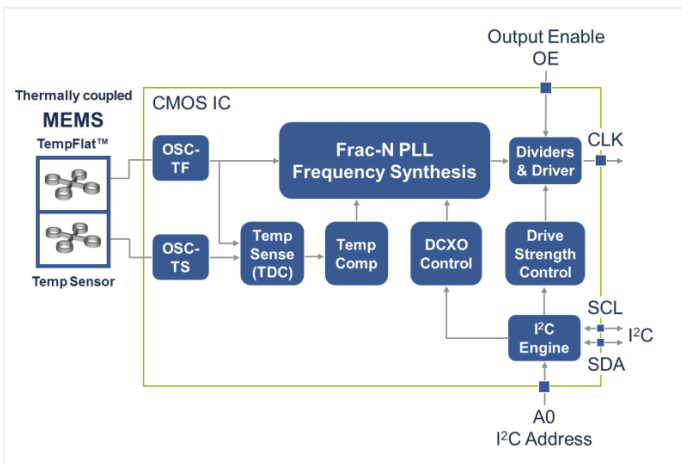


Figure 27. Block Diagram - DCTCXO

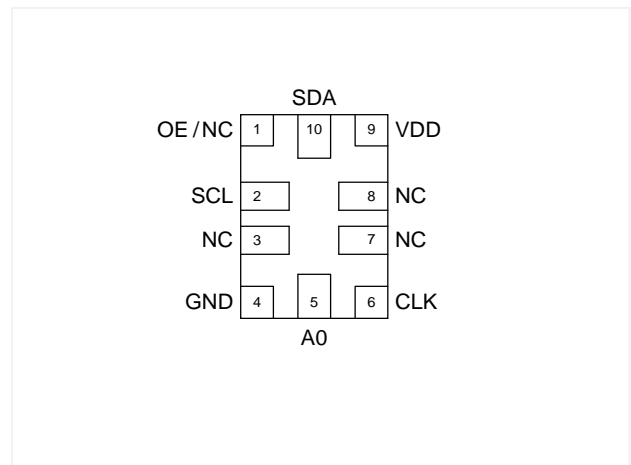


Figure 28. Top-View - DCTCXO

In the DCTCXO mode, the device powers up at the nominal operating frequency and pull range specified by the ordering code. After power-up both the pull range and output frequency can be controlled via I<sup>2</sup>C writes to the respective control registers. The maximum output frequency change is constrained by the pull range limits.

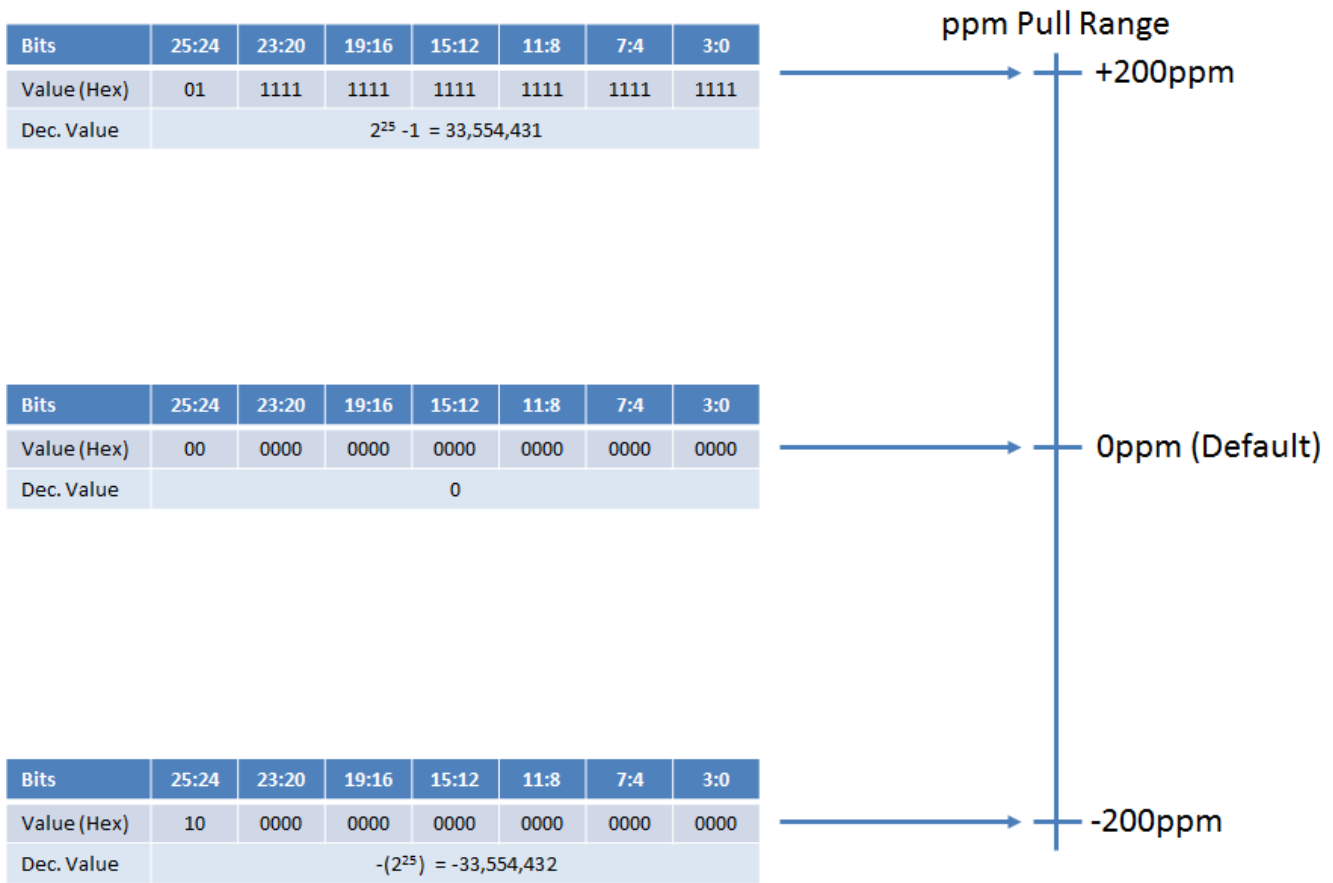
The pull range is specified by the value loaded in the digital pull range control register. The 16 pull range choices are specified in the control register and range from ±6.25ppm to ±3200ppm.

Table 14 below shows the frequency resolution vs. pull range programmed value

**Table 14. Frequency Resolution vs. Pull Range**

Programmed Pull Range	Frequency Resolution
±6.25ppm	$5 \times 10^{-12}$
±10ppm	$5 \times 10^{-12}$
±12.5ppm	$5 \times 10^{-12}$
±25ppm	$5 \times 10^{-12}$
±50ppm	$5 \times 10^{-12}$
±80ppm	$5 \times 10^{-12}$
±100ppm	$5 \times 10^{-12}$
±120ppm	$5 \times 10^{-12}$
±150ppm	$5 \times 10^{-12}$
±200ppm	$5 \times 10^{-12}$
±400ppm	$1 \times 10^{-11}$
±600ppm	$1.4 \times 10^{-11}$
±800ppm	$2.1 \times 10^{-11}$
±1200ppm	$3.2 \times 10^{-11}$
±1600ppm	$4.7 \times 10^{-11}$
±3200ppm	$9.4 \times 10^{-11}$

The ppm frequency offset is specified by the 26 bit DCXO frequency control register in two's complement format as described in the I<sup>2</sup>C Register Descriptions. The power up default value is 000000000000000000000000b which sets the output frequency at its nominal value (0 ppm). To change the output frequency, a frequency control word is written to 0x00[15:0] (Least Significant Word) and 0x01[9:0] (Most Significant Word). The LSW value should be written first followed by the MSW value; the frequency change is initiated after the MSW value is written.



**Figure 29. Pull range and Frequency Control Word**

Figure 29 shows how the two's complement signed value of the frequency control word sets the output frequency within the ppm pull range set by 0x02:[3:0]. This example shows use of the ±200 ppm pull range. Therefore to set the desired output frequency, one just needs to calculate the fraction of full scale value ppm, convert to two's complement binary and then write the values to the frequency control registers.

The following formula generates the control word value:

**Control word Value =  $RND((2^{25}-1) * \text{ppm shift from nominal/pull range})$** , where RND is the rounding function which rounds the number to the nearest whole number. Two examples follow, assuming the ±200 ppm pull range:

#### Example 1:

- Default Output Frequency = 19.2 MHz
- Desired Output Frequency = 19.201728 MHz (+90 ppm)

$2^{25}-1$  corresponds to +200 ppm, and the fractional value required for +90 ppm can be calculated as follows.

- $90 \text{ ppm} / 200 \text{ ppm} * (2^{25}-1) = 15,099,493.95$ .

Rounding to the nearest whole number yields 15,099,494 and converting to two's complement gives a binary value of 111001100110011001100110 and E66666 in hex.

#### Example 2:

- Default Output Frequency = 10 MHz
- Desired Output Frequency = 9.998 MHz (-50 ppm)

Following the formula shown above,

- $(-50 \text{ ppm} / 200 \text{ ppm}) * (2^{25}) = -8,388,607.75$ .

Rounding to the nearest whole number results in -8,388,608.

Converting to two's complement binary results in 111000000000000000000000 and 3800000 in hex.

To summarize, the procedure for calculating the frequency control word associated with a given ppm offset is as follows:

- 1) Calculate the fraction of the half pull range needed. For example, if the total pull range is set for ±100 ppm and a +20 ppm shift from the nominal frequency is needed, this fraction is  $20 \text{ ppm} / 100 \text{ ppm} = 0.2$
- 2) Multiply this fraction by the full half scale word value,  $2^{25}-1 = 33,554,431$ , round to the nearest whole number and convert the result to two's complement binary. Following the +20ppm example, this value is  $0.2 * 33,554,431 = 6,710,886.2$  and rounded to 6,710,886.
- 3) Write the two's complement binary value starting with the Least Significant Word (LSW) 0x00[16:0], followed by the Most Significant Word (MSW), 0x01[9:0]. If the user desires that the output remains enabled while changing the frequency, a 1 must also be written to the OE control bit 0x01[10] if the device has software OE Control Enabled.

It is important to note that the maximum Digital Control update rate is 38 kHz regardless of I<sup>2</sup>C bus speed.

## I<sup>2</sup>C Control Registers

The DCTCXO option enables control of frequency pull range, frequency pull value, Output Enable and drive strength control via I<sup>2</sup>C writes to the control registers. Table 15 below shows the register map summary and the detailed register descriptions follow.

**Table 15. Register Map Summary**

Address	Bits	Access	Description
0x00	[15:0]	RW	DIGITAL FREQUENCY CONTROL LEAST SIGNIFICANT WORD (LSW)
0x01	[15:11]	R	NOT USED
	[10]	RW	OE Control. This bit is only active if the output enable function is under software control. If the device is configured for hardware control using the OE pin, writing to this bit has no effect.
	[9:0]	RW	DIGITAL FREQUENCY CONTROL MOST SIGNIFICANT WORD (MSW)
0x02	[15:4]	R	NOT USED
	[3:0]	RW	DIGITAL PULL RANGE CONTROL
0x05	[15:4]	R	NOT USED
	[3:0]	RW	PULL-UP DRIVE STRENGTH CONTROL
0x06	[15:4]	R	NOT USED
	[3:0]	RW	PULL-DOWN DRIVE STRENGTH CONTROL

## Register Descriptions

### Register Address: 0x00. Digital Frequency Control Least Significant Word (LSW)

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Access	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW
Default	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Name	DIGITAL FREQUENCY CONTROL LEAST SIGNIFICANT WORD (LSW)[15:0]															

Bits	Name	Access	Description
15:0	DIGITAL FREQUENCY CONTROL LEAST SIGNIFICANT WORD	RW	<p>Bits [15:0] are the lower 16 bits of the 26 bit FrequencyControlWord and are the Least Significant Word (LSW). The upper 10 bits are in register 0x01[9:0] and are the Most Significant Word (MSW). The lower 16 bits together with the upper 10 bits specify a 26-bit frequency control word.</p> <p>This power-up default values of all 26 bits are 0 which sets the output frequency at its nominal value. After power-up, the system can write to these two registers to pull the frequency across the pull range. The register values are two's complement to support positive and negative control values. The LSW value should be written before the MSW value because the frequency change is initiated when the new values are loaded into the MSW. More details and examples are discussed in the next section.</p>

**Register Address: 0x01. OE Control, Digital Frequency Control Most Significant Word (MSW)**

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Access	R	R	R	R	R	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW	RW
Default	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Name	NOT USED					OE	DCXO FREQUENCY CONTROL[9:0] MSW									

Bits	Name	Access	Description
15:11	NOT USED	R	Bits [15:10] are read only and return all 0's when read. Writing to these bits has no effect.
10	OE Control	RW	Output Enable Software Control. Allows the user to enable and disable the output driver via I <sup>2</sup> C. 0 = Output Disabled (Default) 1 = Output Enabled  This bit is only active if the Output Enable function is under software control. If the device is configured for hardware control using the OE pin, writing to this bit has no effect.
9:0	DIGITAL FREQUENCY CONTROL MOST SIGNIFICANT WORD (MSW)	RW	Bits [9:0] are the upper 10 bits of the 26 bit FrequencyControlWord and are the Most Significant Word (MSW). The lower 16 bits are in register 0x00[15:0] and are the Least Significant Word (LSW). These lower 16 bits together with the upper 10 bits specify a 26-bit frequency control word.  This power-up default values of all 26 bits are 0 which sets the output frequency at its nominal value. After power-up, the system can write to these two registers to pull the frequency across the pull range. The register values are two's complement to support positive and negative control values. The LSW value should be written before the MSW value because the frequency change is initiated when the new values are loaded into the MSW. More details and examples are discussed in the next section.

**Register Address: 0x02. DIGITAL PULL RANGE CONTROL<sup>[8]</sup>**

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Access	R	R	R	R	R	R	R	R	R	R	R	R	RW	RW	RW	RW
Default	0	0	0	0	0	0	0	0	0	0	0	0	X	X	X	X
Name	NONE												DIGITAL PULL RANGE CONTROL			

**Notes:**

8. Default values are factory set but can be over-written after power-up.

Bits	Name	Access	Description
15:4	NONE	R	Bits [15:4] are read only and return all 0's when read. Writing to these bits has no effect.
3:0	DIGITAL PULL RANGE CONTROL	RW	<p>Sets the digital pull range of the DCXO. The table below shows the available pull range values and associated bit settings. The default value is factory programmed</p> <p><b>Bit</b></p> <p><b>3 2 1 0</b></p> <p>0 0 0 0: ±6.25ppm                      0 0 0 1: ±10ppm                      0 0 1 0: ±12.5ppm                      0 0 1 1: ±25ppm                      0 1 0 0: ±50ppm                      0 1 0 1: ±80ppm                      0 1 1 0: ±100ppm                      0 1 1 1: ±125ppm                      1 0 0 0: ±150ppm                      1 0 0 1: ±200ppm                      1 0 1 0: ±400ppm                      1 0 1 1: ±600ppm                      1 1 0 0: ±800ppm                      1 1 0 1: ±1200ppm                      1 1 1 0: ±1600ppm                      1 1 1 1: ±3200ppm</p>

**Register Address: 0x05. PULL-UP DRIVE STRENGTH CONTROL**

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Access	R	R	R	R	R	R	R	R	R	R	R	R	RW	RW	RW	RW
Default	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Name	NONE												PULL-UP DRIVE STRENGTH CONTROL			

Bits	Name	Access	Description
15:4	NONE	R	Bits [15:4] are read only and return all 0's when read. Writing to these bits has no effect.
3:0	PULL-UP DRIVE STRENGTH CONTROL	RW	<p>Sets the pull-up drive strength of the output driver. The below table shows the range of values.</p> <p><b>Bit</b> <b>3 2 1 0</b></p> <p>0 0 0 0: 5x (Default)                      0 0 0 1: 6x                      0 0 1 0: 7x                      0 0 1 1: 8x                      0 1 0 0: 9x                      0 1 0 1: 10x                      0 1 1 0: 11x                      0 1 1 1: 12x                      1 0 0 0: 13x                      1 0 0 1: 14x                      1 0 1 0: 15x                      1 0 1 1: 16x                      1 1 0 0: 17x                      1 1 0 1: 18x                      1 1 1 0: 19x                      1 1 1 1: 20x</p>

**Register Address: 0x06. PULL-DOWN DRIVE STRENGTH CONTROL**

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Access	R	R	R	R	R	R	R	R	R	R	R	R	RW	RW	RW	RW
Default	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Name	NONE												PULL-DOWN DRIVE STRENGTH CONTROL			

Bits	Name	Access	Description
5:4	NONE	R	Bits [15:4] are read only and return all 0's when read. Writing to these bits has no effect.
3:0	PULL-DOWN DRIVE STRENGTH CONTROL	RW	<p>Sets the pull-down drive strength of the output driver. The below table shows the range of values.</p> <p><b>Bit</b> <b>3 2 1 0</b></p> <p>0 0 0 0: 5x (Default)                      0 0 0 1: 6x                      0 0 1 0: 7x                      0 0 1 1: 8x                      0 1 0 0: 9x                      0 1 0 1: 10x                      0 1 1 0: 11x                      0 1 1 1: 12x                      1 0 0 0: 13x                      1 0 0 1: 14x                      1 0 1 0: 15x                      1 0 1 1: 16x                      1 1 0 0: 17x                      1 1 0 1: 18x                      1 1 1 0: 19x                      1 1 1 1: 20x</p>

### Serial Interface Configuration Description

The SiT5155 may be ordered with the I<sup>2</sup>C interface to access registers which control the DCTCXO frequency pull range, frequency pull value, and output drive strength. The SiT5155 I<sup>2</sup>C slave only interface supports clock speeds up to 1 MHz. The SiT5155 I<sup>2</sup>C module is based on the I<sup>2</sup>C specification, UM1024 (Rev.6 April 4, 2014 of NXP Semiconductor).

### Serial Signal Format

The SDA line must be stable during the high period of the SCL. SDA transitions are allowed only during SCL low level for data communication. Only one transition is allowed during the low SCL state to communicate one bit of data. Figure 30 shows the detailed timing diagram.

The idle I<sup>2</sup>C bus state occurs when both SCL and SDA are not being driven by any master and are therefore in a logic HI state due to the pull up resistors. Every transaction begins with a START (S) signal and ends with a STOP (P) signal. A START condition is defined by a high to low transition on the SDA while SCL is high. A STOP condition is defined by a low to high transition on the SDA while SCL is high. START and STOP conditions are always generated by the master. This slave module also supports repeated START (Sr) condition which is same as START condition instead of STOP condition (Blue color line shows repeated START in Figure 31).

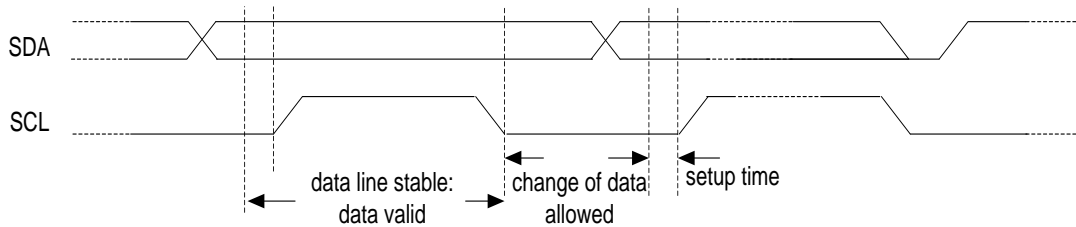


Figure 30. Data and clock timing relation in I<sup>2</sup>C bus

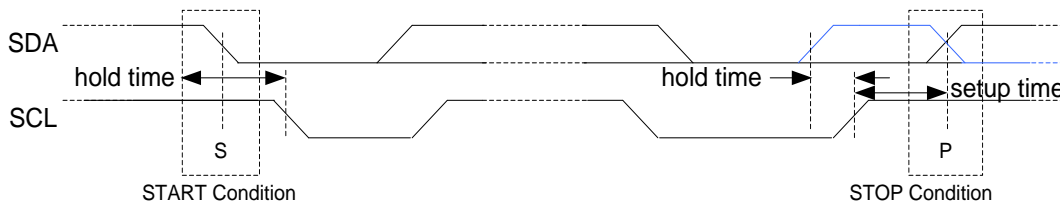


Figure 31. START and STOP (or repeated START) condition

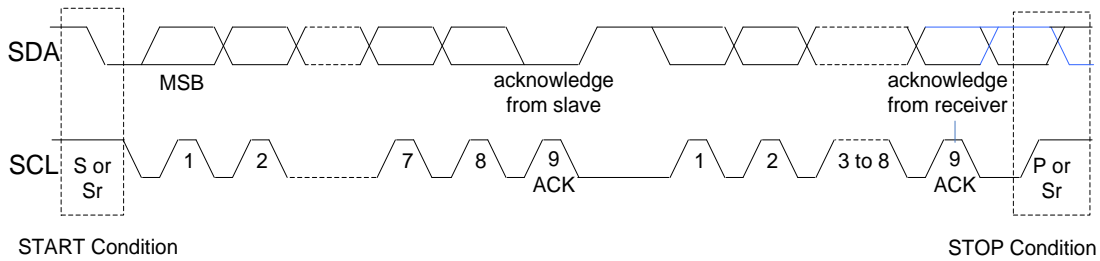
### Parallel Signal Format

Every data byte is eight bits long. The number of bytes that can be transmitted per transfer is unrestricted. Data is transferred with the MSB (Most Significant Bit) first. The detailed data transfer format is shown in Figure 33 below.

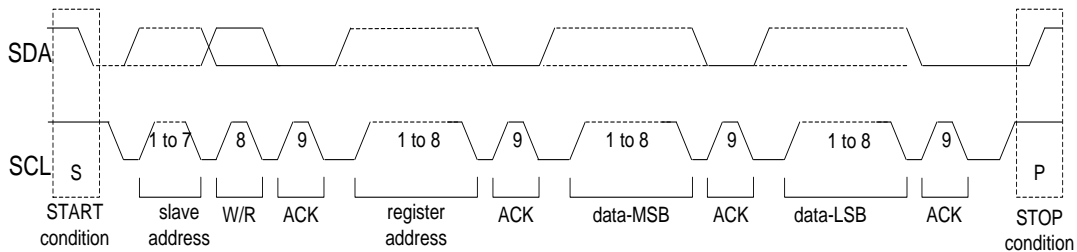
The acknowledge bit must occur after every byte transfer and it allows the receiver to signal the transmitter that the byte was successfully received and another byte may be sent. The acknowledge signal is defined as follows: the transmitter releases the SDA line during the acknowledge clock pulse so the receiver can pull the SDA line low and it remains stable low during the high period of this clock pulse. Setup and hold times must also be taken into account. When SDA remains high during this ninth clock pulse, this is defined as the Not-Acknowledge signal (NACK). The master can then generate either a STOP condition to abort the transfer, or a repeated START condition to start a new transfer. The only condition that leads to the generation of NACK from the SiT5155 is when the transmitted address does not match the slave address. When the master is reading data from the SiT5155, the SiT5155 expects the ACK from the master at the end of received data, so that the slave releases the SDA line and the master can generate the STOP or repeated START. If there is a NACK signal at the end of the data, then the SiT5155 tries to send the next data. If the first bit of the next data is “0”, then the SiT5155 holds the SDA line to “0”, thereby blocking the master from generating a STOP/(re)START signal.

### Parallel Data Format

This I<sup>2</sup>C slave module supports 7-bit device addressing format. The 8<sup>th</sup> bit is a read/write bit and “0” indicates a read transaction and a “1” indicates a write transaction. The register addresses are 8-bits long with an address range of 0 to 255 (00h to FFh). Auto address incrementing is supported which allows data to be transferred to contiguous addresses without the need to write each address beyond the first address. Since the maximum register address value is 255, the address will roll from 255 back to 0 when auto address incrementing is used. Obviously, auto address incrementing should only be used for writing to contiguous addresses. The data format is 16-bit (two bytes) with the most significant byte being transferred first.

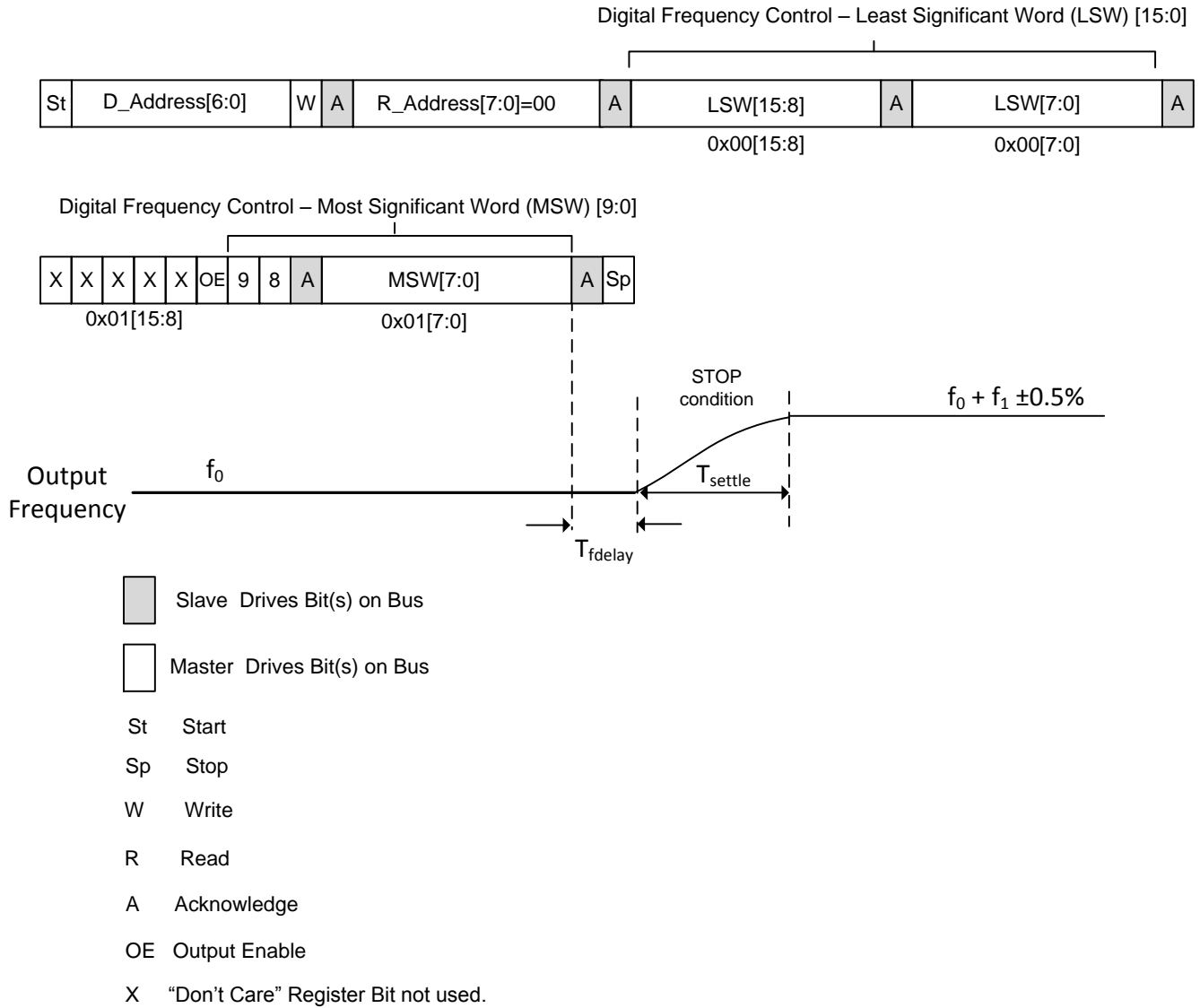


**Figure 32. Parallel Signaling Format**



**Figure 33. Parallel Data Byte Format**

Figure 34 below shows the I<sup>2</sup>C sequence for writing the 4-byte control word using auto address incrementing.



**Figure 34. Writing the Frequency Control Word**

**Table 16. DCTCXO Delay and Settling Time**

Parameter	Symbol	Minimum	Typical	Maximum	Units	Notes
Frequency Change Delay	$T_{fdelay}$	–	22	–	µsec	
Frequency Settling Time	$T_{settle}$	–	30	–	µsec	Time to settle to 1% of final frequency value

## I<sup>2</sup>C Timing Specification

The below timing diagram and table illustrate the timing relationships for both master and slave.

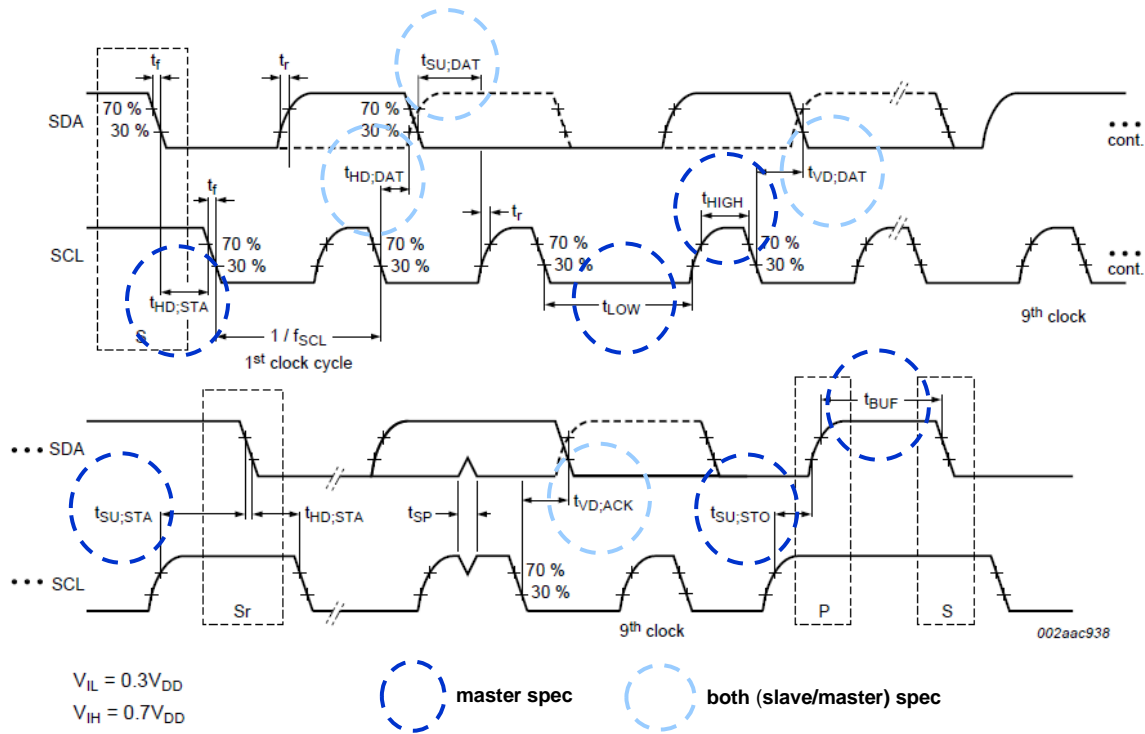


Figure 35. I<sup>2</sup>C Timing Diagram

Table 17. I<sup>2</sup>C Timing Requirements

Parameter	Speed Mode	Value	Unit
$t_{SETUP}$	FM+ (1 MHz)	> 50	nsec
	FM (400KHz)	> 100	nsec
	SM (100KHz)	> 250	nsec
$t_{HOLD}$	FM+ (1 MHz)	> 0	nsec
	FM (400KHz)	> 0	nsec
	SM (100KHz)	> 0	nsec
$t_{VD,AWK}$	FM+	> 450	nsec
	FM (400KHz)	> 900	nsec
	SM (100KHz)	> 3450	nsec
$t_{VD,DAT}$		NA (s-awk + s-data)/(m-awk/s-data)	

## I<sup>2</sup>C Device Address Modes

There are two I<sup>2</sup>C address modes:

- 1) Factory Programmed Mode. The lower 4 bits of the 7-bit device address are set by ordering code as shown in Table 18 below. There are 16 factory programmed addresses available. In this mode, pin 5 is NC and the A0 I<sup>2</sup>C address pin control function is not available.
- 2) A0 Pin Control. This mode allows the user to select between two I<sup>2</sup>C Device addresses as shown in Table 19.

**Table 18. Factory Programmed I<sup>2</sup>C Address Control<sup>[9]</sup>**

I <sup>2</sup> C Address Ordering Code	Device I <sup>2</sup> C Address
0	1100000
1	1100001
2	1100010
3	1100011
4	1100100
5	1100101
6	1100110
7	1100111
8	1101000
9	1101001
A	1101010
B	1101011
C	1101100
D	1101101
E	1101110
F	1101111

**Notes:**

9. Table 18 is only valid for the DCTCXO device option which supports I<sup>2</sup>C Control.

**Table 19. Pin Selectable I<sup>2</sup>C Address Control<sup>[9]</sup>**

A0 Pin 5	I <sup>2</sup> C Address
0	1100010
1	1101010

**Notes:**

- Table 19 is only valid for the DCTCXO device option which supports I<sup>2</sup>C control and A0 Device Address Control Pin.

Schematic Example

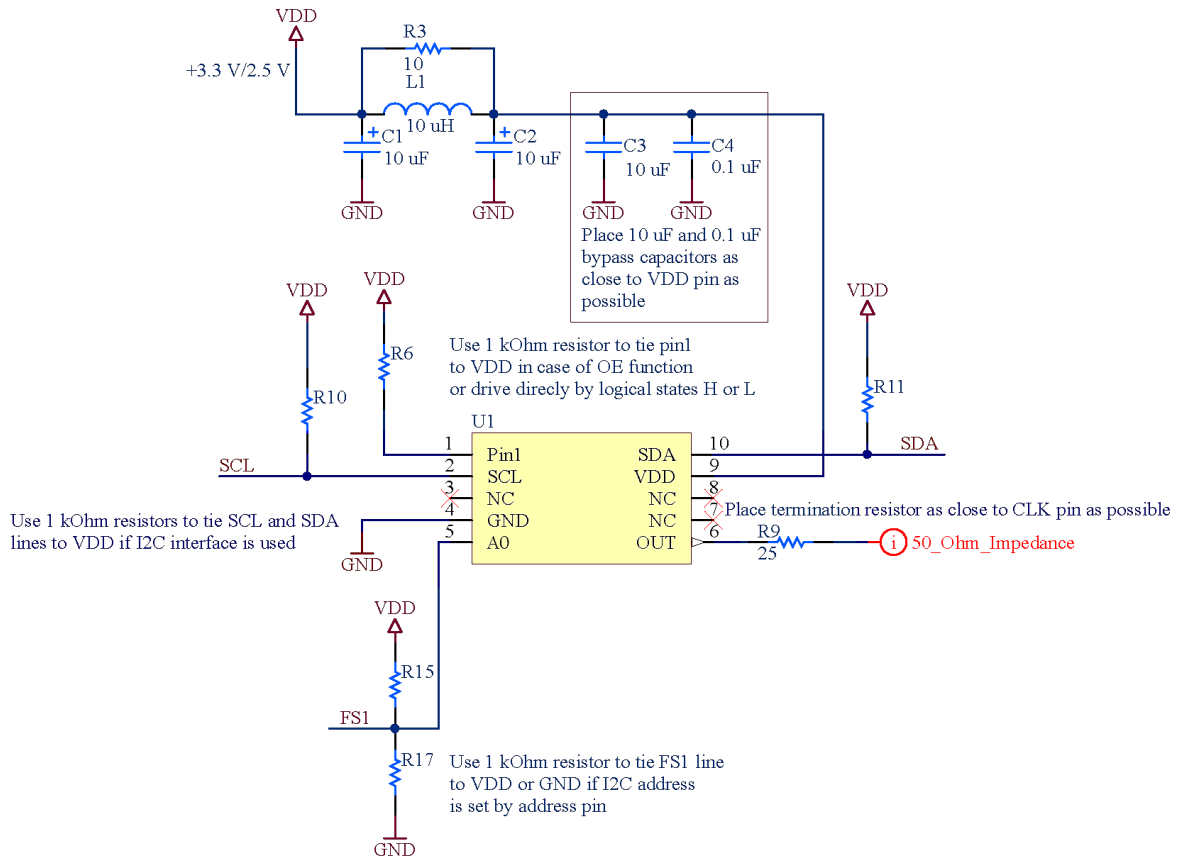


Figure 36. Schematic Example - DCTCXO

## Dimensions and Patterns

**Package Size – Dimensions (Unit: mm)**

Dimension Table					
	Symbol	Min	Nom	Max	
TOTAL THICKNESS	A	0.840	0.950	1.060	
BODY SIZE	X	D	4.850	5.000	5.150
	Y	E	3.050	3.200	3.350
LEAD PITCH	e	1.070	1.200	1.330	
	e1	1.220	1.350	1.480	
	e2	0.970	1.100	1.230	
LEAD LENGTH	L	0.970	1.100	1.230	
	L1	0.770	0.900	1.030	
LEAD WIDTH	W	0.470	0.600	0.730	
	W1	0.670	0.800	0.930	
	W2	0.470	0.600	0.730	

Package Outline	
10L Ceramic	POD-036-RevA
5.0x3.2x0.87	
2017/08/07	

**Recommended Land Pattern (Unit: mm)**

Solder Print Layout	
10L Ceramic	SPL-001-RevA
5.0x3.2x0.87	
2017/06/20	

### Layout Guidelines

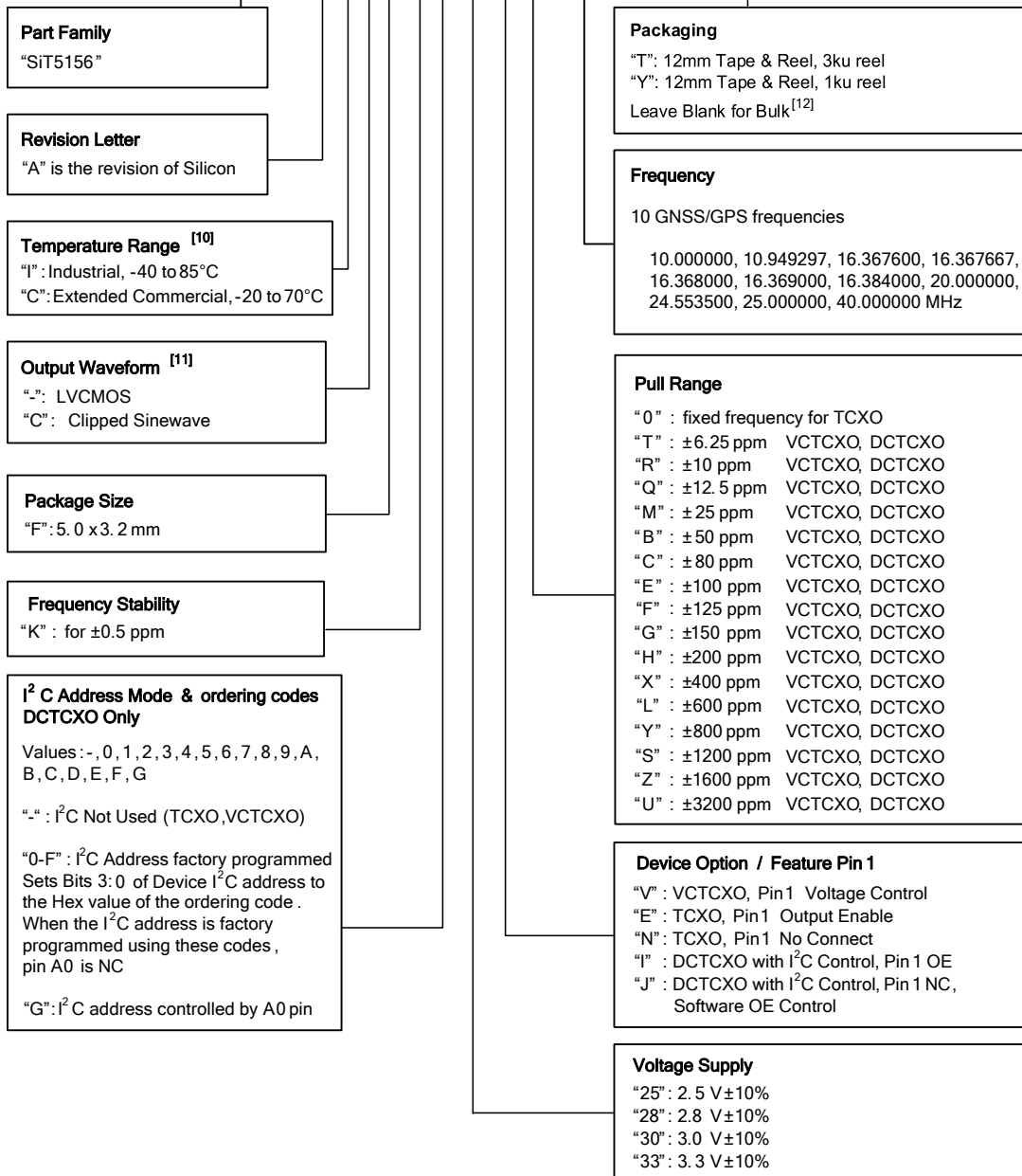
- SiT5155 uses internal regulators to minimize the impact of the power supply noise. For further reduction of noise, it is essential to use two bypass capacitors (0.1 µF and 10 µF). Place the bypass capacitors as close to the Vdd as possible, typically within 1 to 2 mm. Ensure that the 0.1µF cap is the closest to the device Vdd and GND power pins
- It is also recommended to connect all NC pins to the ground plane and place multiple vias under the GND pin for maximum heat dissipation.
- For additional layout recommendations, refer to the following link:  
<http://www.sitime.com/support2/documents/AN10006-Best-Design-Layout-Practices.pdf>

### Manufacturing Guidelines

- No Ultrasonic or Megasonic Cleaning: Do not subject the SiT5155 to an ultrasonic or megasonic cleaning environment. Permanent damage or long-term reliability issues to the device may occur in such an event.
- No external cover. Unlike legacy quartz TCXOs, the SiT5155 is engineered to operate reliably without performance degradation, in the presence of ambient disturbers such as airflow and sudden temperature changes. Therefore, the use of an external cover typical of quartz TCXOs is not needed.
- Reflow profile, per JESD22-A113D.
- For additional manufacturing guidelines and marking/tape-reel instructions, refer to the following link:  
[http://www.sitime.com/component/docman/doc\\_download/243-manufacturing-notes-for-sitime-oscillators](http://www.sitime.com/component/docman/doc_download/243-manufacturing-notes-for-sitime-oscillators)

**Ordering Information**

**SiT5155AC-FK-33VQ-10.000000T**



**Notes:**

- 10. Contact [SiTime](#) for higher temperature range options
- 11. "-" corresponds to the default rise/fall time for LVCMOS output as specified in Table 1 (Electrical Characteristics). Contact [SiTime](#) for other rise/fall time options for best EMI.
- 12. Bulk is available for sampling only
- 13. "0" is selected when the device is configured as a TCXO (pin 1 = "E" or "N"). "T" to "U" are applicable in VCTCXO mode (pin 1 = "V") and DCTCXO mode (pin 1 = "E" or "N")

**Table 20. Ordering Codes for Supported Tape & Reel Packing Method**

Device Size (mm x mm)	16 mm T&R(3ku)	16 mm T&R(1ku)	12 mm T&R(3ku)	12 mm T&R(1ku)	8 mm T&R(3ku)	8 mm T&R(1ku)
5.0 x 3.2	-	-	T	Y	-	-

Table 21. Additional Information

Document	Description	Download Link
Time Machine II	MEMS oscillator programmer	<a href="http://www.sitime.com/support/time-machine-oscillator-programmer">http://www.sitime.com/support/time-machine-oscillator-programmer</a>
Field Programmable Oscillators	Devices that can be programmable in the field by Time Machine II	<a href="http://www.sitime.com/products/field-programmable-oscillators">http://www.sitime.com/products/field-programmable-oscillators</a>
Manufacturing Notes	Tape & Reel dimension, reflow profile and other manufacturing related info	<a href="http://www.sitime.com/component/docman/doc_download/243-manufacturing-notes-for-sitime-oscillators">http://www.sitime.com/component/docman/doc_download/243-manufacturing-notes-for-sitime-oscillators</a>
Qualification Reports	RoHS report, reliability reports, composition reports	<a href="http://www.sitime.com/support/quality-and-reliability">http://www.sitime.com/support/quality-and-reliability</a>
Performance Reports	Additional performance data such as phase noise, current consumption and jitter for selected frequencies	<a href="http://www.sitime.com/support/performance-measurement-report">http://www.sitime.com/support/performance-measurement-report</a>
Termination Techniques	Termination design recommendations	<a href="http://www.sitime.com/support/application-notes">http://www.sitime.com/support/application-notes</a>
Layout Techniques	Layout recommendations	<a href="http://www.sitime.com/support/application-notes">http://www.sitime.com/support/application-notes</a>

Table 22. Revision History

Version	Release Date	Change Summary
0.1	05/10/2016	First release, advanced information
0.15	08/04/2016	Replaced QFN package with SOIC-8 package Added 10 µF bypass cap requirement Updated test circuits to reflect both new bypass cap requirement and SOIC-8 package Update Table 1 (Electrical Characteristics)
0.16	09/12/2016	Updated test circuit diagrams
0.2	09/21/2016	Revised Table 1 (Electrical Characteristics)
0.51	08/21/2017	Changed to preliminary Added DCTCXO mode Added I2C information Updated 5.0x3.2 mm package dimensions Updated test circuits Updated Table 1 (Electrical Characteristics) Updated part ordering info Misc. corrections

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